Layer Name Type Material Thickness (mm) Color Epsilon R Loss Tangent F.Silkscreen Top Silk Screen Not specified 0 mm Not specified 1 F.Paste Top Solder Paste 0 0 mm Not specified 0.01 mm F.Mask Top Solder Mask Not specified 3.3 F.Cu copper 0.035 mm Dielectric 1 core FR4 1.51 mm Not specified 4.5 0.02 B.Cu copper 0.035 mm B.Mask Bottom Solder Mask Not specified 0.01 mm Not specified 3.3 0 B.Paste Bottom Solder Paste 0 B.Silkscreen Bottom Silk Screen Not specified 0 mm Not specified 1

BOARD CHARACTERISTICS

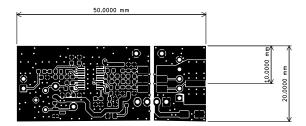
Copper Layer Count: Board Thickness: 1.6000 mm

Board overall dimensions: 50.0000 mm x 20.0000 mm

Min track/spacing: 0.1500 mm / 0.1500 mm Min hole diameter: 0.3000 mm

Copper Finish: Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No



Sheet:

File: current_probe.kicad_pcb

litle: Low-Noise Amplifier Current Probe		
Size: A4	Date: 2023-10-07	Rev:
KiCad E.D.A. kid	ad 7.0.1	ld: 1/1